PMP4472 BOM

Quantity	Designator	Description	Footprint	Comment	MFR
1	C1	CAP;100nF,CER,275V(UL CSA 250V),10%,CBB,17x6x12,TH	CAPRR_15D24_17D0X6D0X12D0	NA	
1	C2	CAP;2.2nF,CER,1KV,5%,Z5U,9.5x7.0x9.5,TH	CAPRR_10D16_9D5X7D0X9D5	470pF	
1	C3	CAP;15uF,ALUM,400V,20%,ALUM,C10X16,DIP	CAPAE1000X1600_TH	15uF	
1	C4	CAP;220pF,CER,630V,5%,COG,1206,SMD	C1206	220pF	
1	C15	Capacitor, Ceramic	0603	0.1uF	
2	C6, C17	Capacitor, Ceramic	C0603	NA	
1	C8	CAP;1500uF,ALUM,6.3V,20%,ALUM,C10X12,DIP	CAPAE1000X1600_TH	1500uF	
1	C9, C13	Capacitor, Ceramic	C0603	100nF	
2	C10, C18	Capacitor, Ceramic	C1206	NA	
1	C11	Capacitor, Ceramic	C1210	10uF/35V	
1	C12	CAP;100nF,CER,275V(UL CSA 250V),10%,CBB,17x6x12,TH	CAPRR_15D24_17D0X6D0X12D0	100nF	
1	C21	Capacitor, Ceramic	0603	10pF/50V	
1	C50	Capacitor, Ceramic	0603	1uF/25V	
1	C23	Capacitor, Ceramic	0603	3.3nF	
1	C14	CAP;1nF,CER,2KV,10%,X7R,1812,SMD	C1812	NA	
1	C16	Capacitor, Ceramic	C0603	47nF/50V	
2	C19, C20	Capacitor, Ceramic	C1206	22uF	Murata
1	C28	Capacitor, Ceramic	C1206	22uf 6.3V	Murata
1	CON1	CONN HEADER;2x3P,5.08mm,VERT,DIP,LSF-SMT,TIN	CON_LSF-SMT-5D08-C3P6-180	5.08mm LSF-SMT-C3P6	
1	CON2	CONN HEADER;2x3P,3.81mm,VERT,DIP,LSF-SMT,TIN	CON_LSF-SMT-3D81-C3P6-180	3.81mm LSF-SMT-C3P6	
1	CON3	CONN HEADER;2x4P,2.00mm 7.4mm high,VERT,DIP,PIN,TIN	CON_2D00_2X4_TH	2.00mm 2x4 TH HEADER	
1	D1	BRIDGE;BRIDGE RECTIFIER,600V,1A,DFS,4PIN	DIODE_DFS	DF06S	
1	D2	DIODE;GLASS PASSIVATED,600V,1A,POWERDI123,SMD	POWERDI123	DFLR1600	
1	D3	DIODE;SCHOTTKY,40V,10A,POWERDI5,SMD	POWERDI5	PDS1040L	
1	D4	DIODE;HIGH VOLTAGE SWITCHING DIODE,250V,200mA,SOD323,SMD	SOD-323	BAS21HT1G	
2	D5, D7	DIODE TVS	SMB	NA	
1	D6	DIODE TVS	SMB	NA	
1	F1	FUSE;1A,250V,Time-Lag,8.5x4x8.0,TH	F5D08_8D5X4D0X8D0MM	1A	
1	G1	DIODES;gas discharge tube,SMD		NA	
1	L1	SMD Inductor WE-PD S 3.3uH 3.1A	Inductor 744778003	3.3uH	

1	L2	IND,L16D0X12D0X17D5MM,TH	L16D0X12D0X17D5MM	10mH	
1	L3	IND;2Kohm 10MHz,SRF4532-101Y,SMD,SHIELDED,FERRITE	L4D5X3D2X2D8MM	NA	
1	Q1	MOSFET N-CH 600V 2A IPAK	TO-251AB	STD2HNK60Z-1	
1	R1	RES;300Kohm,1/4W,5%,1206,SMD	R1206	300K	
2	R2, R10	RES;300ohm,1/4W,5%,1206,SMD	R1206	300R	
1	R3	RES;15ohm,1/8W,5%,0805,SMD	R0805	NA	
1	R4	RES;2.4Kohm,1/4W,5%,1206,SMD	R1206	2.4k	
1	R5	RES;22ohm,1/10W,5%,0603,SMD	0603	22R	
1	R6	RES;68Kohm,1/10W,1%,0603,SMD	0603	68K 1%	
1	R7	RES;1Kohm,1/8W,5%,0805,SMD	0805	1K	
2	R16, R17	RES;2.2ohm,1/8W,5%,0805,SMD	0805	2.2	
1	R8	RES;360Kohm,1/10W,1%,0603,SMD	0603	NA	
1	R9	RES;47Kohm,1/10W,1%,0603,SMD	0603	47K 1%	
1	R11	RES;10ohm,1/10W,1%,0603,SMD	0603	10	
1	R12	RES;510ohm,1/10W,1%,0603,SMD	0603	510	
1	R13	RES;470ohm,1/10W,1%,0603,SMD	0603	470	
2	R14, R21	RES;10Kohm,1/10W,1%,0603,SMD	0603	10K	
1	R18	RES;1Kohm,1/10W,1%,0603,SMD	0603	1K	
1	R20	RES;196Kohm,1/10W,1%,0603,SMD	0603	196K	
1	R23	RES;72.5Kohm,1/10W,1%,0603,SMD	0603	72.5K	
1	R24	RES;22Kohm,1/10W,1%,0603,SMD	0603	22K	
1	RV1	MOV;MOV-10D681K,31V MOV,MOV-10D,2PIN	MOV-10D	NA	
1	RV2	PTC;MZ2-390N,,PTC-T5MMD10MM,2PIN	PTC-T5MMD10MM	NA	
1	T1	FLYBACK TRANSFORMER;8W,3.3V,2.2A,EPC17,TH,SHIELDED	EPC17	TRNSFMR_EPC17	
1	U1	Buck Step Down Regulator with 4.5 to 18 V Input and 0.76 to 7 V Output, -4	DDA-8	TPS54228D	TI
1	U2	IC REG CTRLR FLYBK ISO 7SOIC	SOIC-7	UCC28740	TI
1	U4	4-Pin Phototransistor Optocoupler	OPTOCOUPLER	FOD817	
1	U5	IC VREF SHUNT ADJ SOT23	SOT-23	TL431AIDBZ	TI

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